

Fabrication Drawing

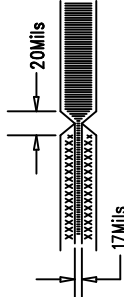
Linear Tech. Corp.  
Demo Circuit 1376A

SIZE	QTY	SYM	PLATED	TOL
187	4	+	YES	+/-0.003
35	17	X	YES	+/-0.003
10	111	□	YES	+/-0.003
63	8	◇	YES	+/-0.003
70	2	⊗	NO	+/-0.003
94	11	⊗	YES	+/-0.003
35	2	⊕	NO	+/-0.003
311	3	⊕	YES	+/-0.003
31	18	⊕	YES	+/-0.003

REVISIONS		
REV	APPR	DATE

NOTES: UNLESS OTHERWISE SPECIFIED:

- ARTWORK P/N Demo Circuit 1376A
- FAB PER IPC-A-600. 6-Layers.
- MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4  
.062 +/- .005 INCH THICKNESS WITH 2 OZ. COPPER FINISH ON TWO OUTER LAYERS AND 1 OZ. COPPER ON FOUR INTERNAL LAYERS.  
FLAMMABILITY RATING: 94 V-2 MINIMUM .
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
- BOARD: SELECTIVE PLATED BOARD. SOLDER MASK OVER BARE COPPER. COLOR: GREEN LPI. GOLD IMMERSION (ENG) BOTH SIDES. SILKSCREEN BOTH SIDES WITH WHITE NON-CONDUCTIVE INK.  
PLATE THRU ALL HOLES WITH COPPER  
MIN. PLATING THICKNESS: 1 OZ. EXCEPT WHERE PLATING NOT REQUIRED
- DRILL: ALL HOLES SHALL BE DRILLED +/- .003 INCH WITH RESPECT TO CTR. OF DRILLED PAD.  
ALL HOLES FINISHED SIZE AFTER PLATING.
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO, DATE CODE OR ELECTRICAL TEST STAMP, BUT YOU MAY MODIFY PAD SIZE TO MEET END FINISH.
- SCORING FOR PANELIZED PCB: "PRODUCTION RUN ONLY"



- DO NOT ALTER SOLDER MASK MAINTAIN .003" OVERSIZE ON SMT PADS. A .005" WEBBING IS REQUIRED BETWEEN SMD PADS.
- PCB'S ARE TO BE ROHS COMPLIANT.

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APPROVALS				LINEAR TECHNOLOGY			
DRAWN	INIT	DATE					
CHECK	LMJ	1/10/08					
DESIGN							
ENGR	B.Shaffer						
				TITLE: LTC3555EUF			
				LTC3555EUF-1/LTC3555-3: High Efficiency USB Power Manager + Triple Step-Down DC/DC Converter			
				SIZE	NONE	Demo Circuit 1376A	REV. A
				DES- SCALE = NONE			
				SHT 1 of 1			